

12A, 650V N-CHANNEL MOSFET

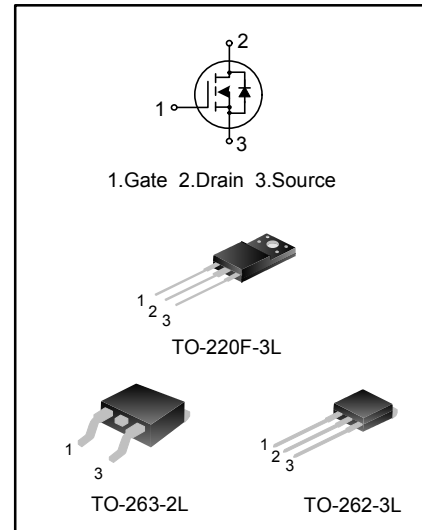
GENERAL DESCRIPTION

SVF12N65CF/K/S is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ high-voltage planar VDMOS technology. The improved process and cell structure have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power supplies, DC-DC converters and H-bridge PWM motor drivers.

FEATURES

- ◆ 12A, 650V, $R_{DS(on)(typ.)} = 0.64\Omega @ V_{GS} = 10V$
- ◆ Low gate charge
- ◆ Low C_{rss}
- ◆ Fast switching
- ◆ Improved dv/dt capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing
SVF12N65CF	TO-220F-3L	SVF12N65CF	Halogen free	Tube
SVF12N65CK	TO-262-3L	SVF12N65CK	Halogen free	Tube
SVF12N65CS	TO-263-2L	12N65CS	Halogen free	Tube
SVF12N65CSTR	TO-263-2L	12N65CS	Halogen free	Tape & Reel

ABSOLUTE MAXIMUM RATINGS (T_C=25°C unless otherwise noted)

Characteristics		Symbol	Ratings			Unit
			SVF12N65 CF	SVF12N65 CK	SVF12N65 CS	
Drain-Source Voltage		V _{DS}	650			V
Gate-Source Voltage		V _{GS}	±30			V
Drain Current	T _C = 25°C	I _D	12			A
	T _C = 100°C		7.6			
Drain Current Pulsed		I _{DM}	48			A
Power Dissipation(T _C =25°C) -Derate above 25°C		P _D	51	209	210	W
			0.41	1.67	1.68	W/°C
Single Pulsed Avalanche Energy (Note 1)		E _{AS}	790			mJ
Operation Junction Temperature Range		T _J	-55~+150			°C
Storage Temperature Range		T _{stg}	-55~+150			°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings			Unit
		SVF12N65 CF	SVF12N65 CK	SVF12N65 CS	
Thermal Resistance, Junction-to-Case	R _{θJC}	2.44	0.6	0.60	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.5	62.5	62.5	°C/W

ELECTRICAL CHARACTERISTICS (T_C=25°C unless otherwise noted)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	650	--	--	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =650V, V _{GS} =0V	--	--	1.0	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	--	--	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D =250μA	2.0	--	4.0	V
Static Drain- Source On State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =6.0A	--	0.64	0.8	Ω
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	--	1390	--	pF
Output Capacitance	C _{oss}		--	156	--	
Reverse Transfer Capacitance	C _{rss}		--	15.2	--	
Turn-on Delay Time	t _{d(on)}	V _{DD} =325V, I _D =12A, V _{GS} =10V, R _G =24Ω (Note 2,3)	--	26	--	ns
Turn-on Rise Time	t _r		--	39	--	
Turn-off Delay Time	t _{d(off)}		--	75	--	
Turn-off Fall Time	t _f		--	39	--	
Total Gate Charge	Q _g	V _{DS} =520V, I _D =12A, V _{GS} =10V (Note 2,3)	--	30	--	nC
Gate-Source Charge	Q _{gs}		--	10	--	
Gate-Drain Charge	Q _{gd}		--	9.4	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction Diode in the MOSFET	--	--	12	A
Pulsed Source Current	I_{SM}		--	--	48	
Diode Forward Voltage	V_{SD}	$I_S=12A, V_{GS}=0V$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$I_S=12A, V_{GS}=0V,$ $dI_F/dt=100A/\mu S$ (Note 2)	--	551	--	ns
Reverse Recovery Charge	Q_{rr}		--	5.2	--	μC

Notes:

1. $L=30mH, I_{AS}=6.0A, V_{DD}=100V, R_G=25\Omega$, starting $T_J=25^\circ C$;
2. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;
3. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS

Figure 1. On-Region Characteristics

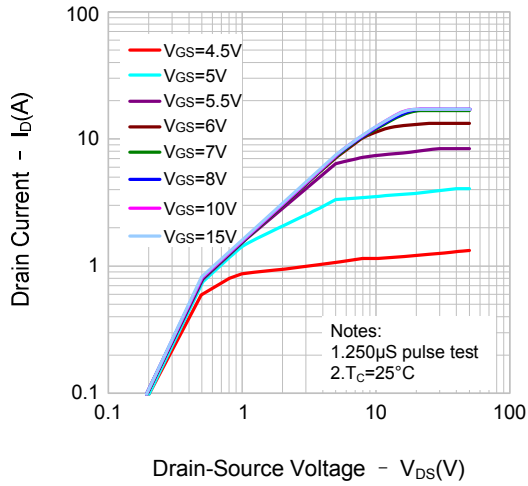


Figure 2. Transfer Characteristics

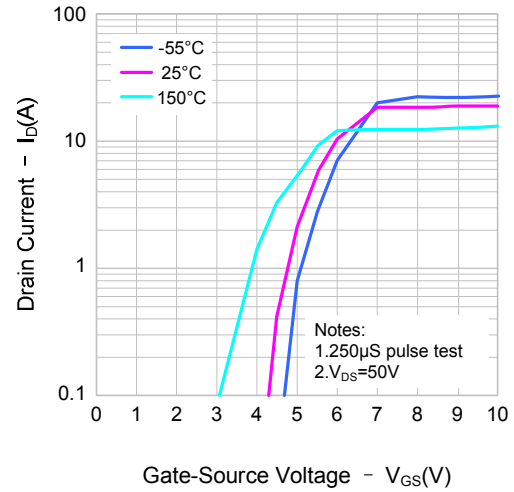


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

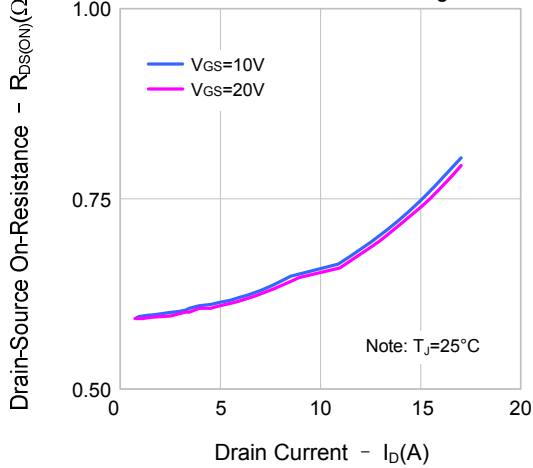


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

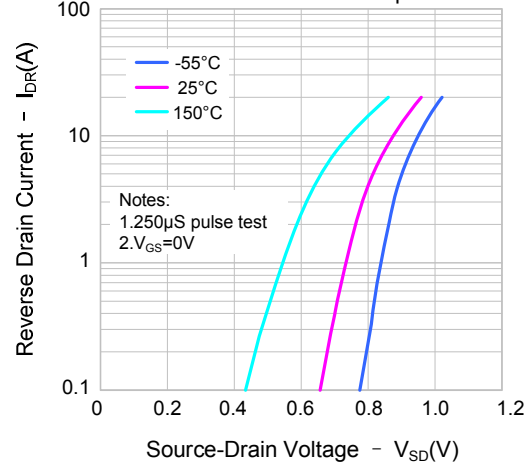


Figure 5. Capacitance Characteristics

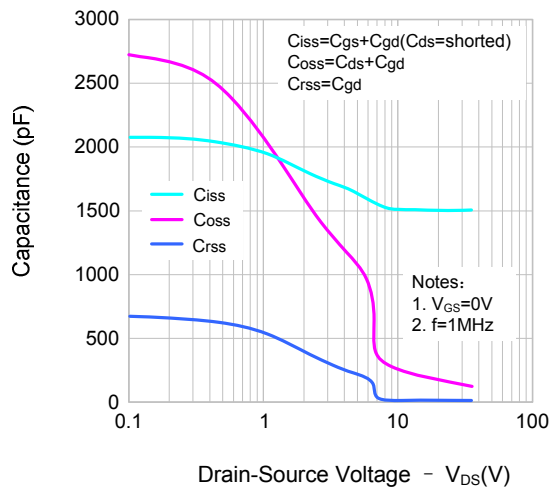
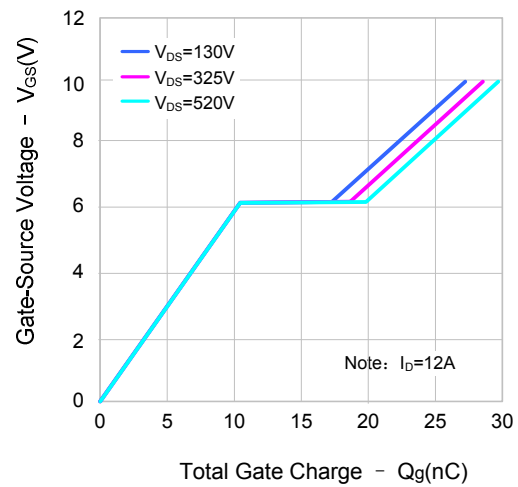


Figure 6. Gate Charge Characteristics



TYPICAL CHARACTERISTICS (continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

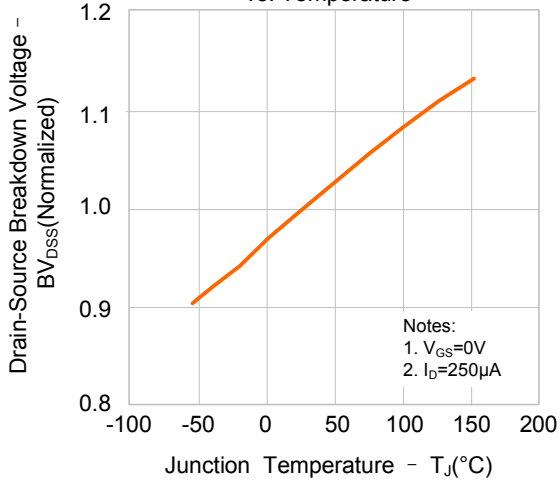


Figure 8. On-resistance vs. Temperature

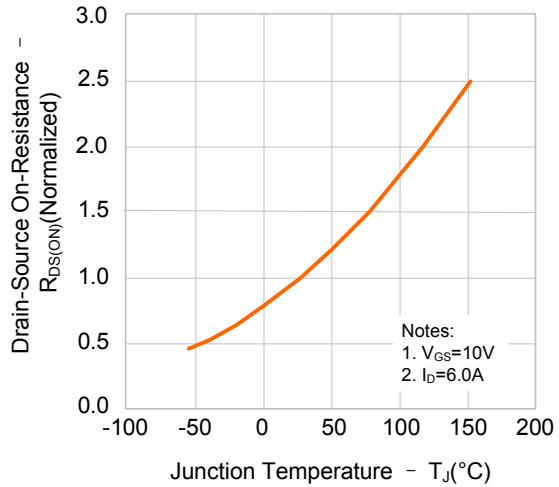


Figure 9-1. Max. Safe Operating Area(SVF12N65CF)

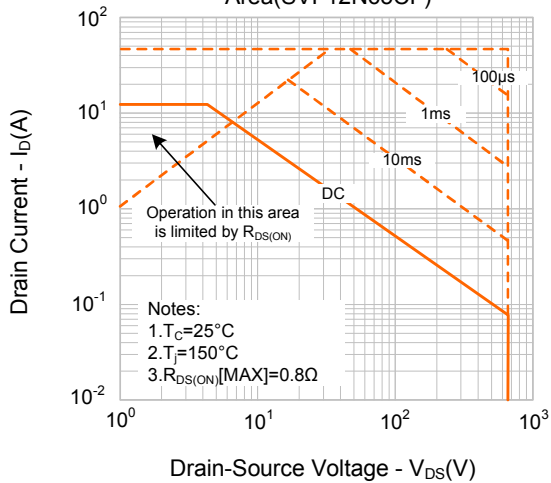


Figure 9-2. Max. Safe Operating Area(SVF12N65CK)

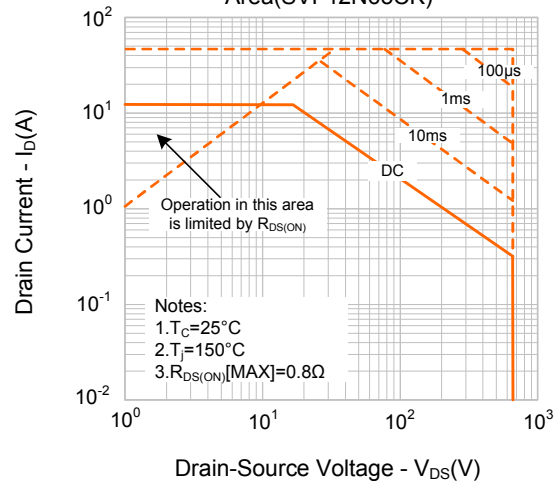


Figure 9-3. Max. Safe Operating Area(SVF12N65CS)

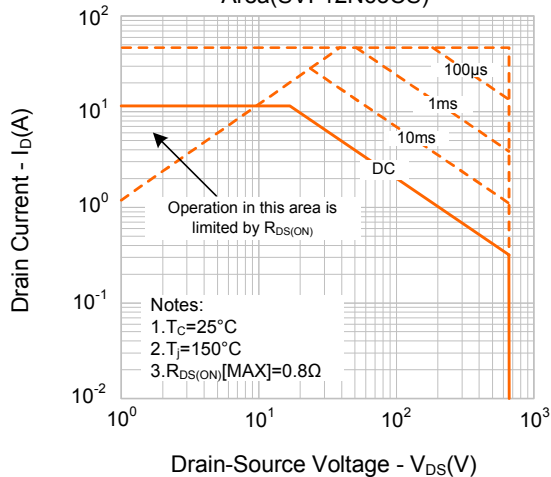
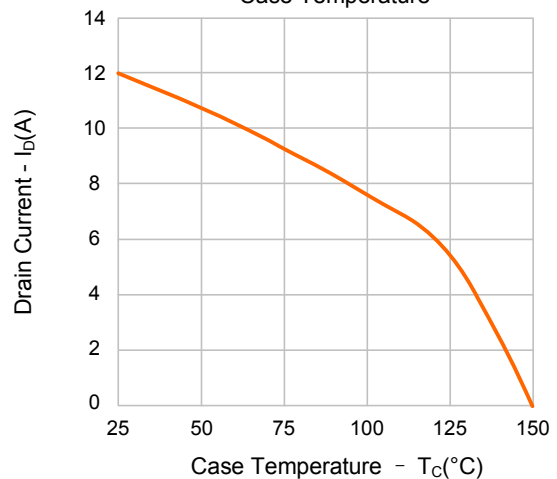
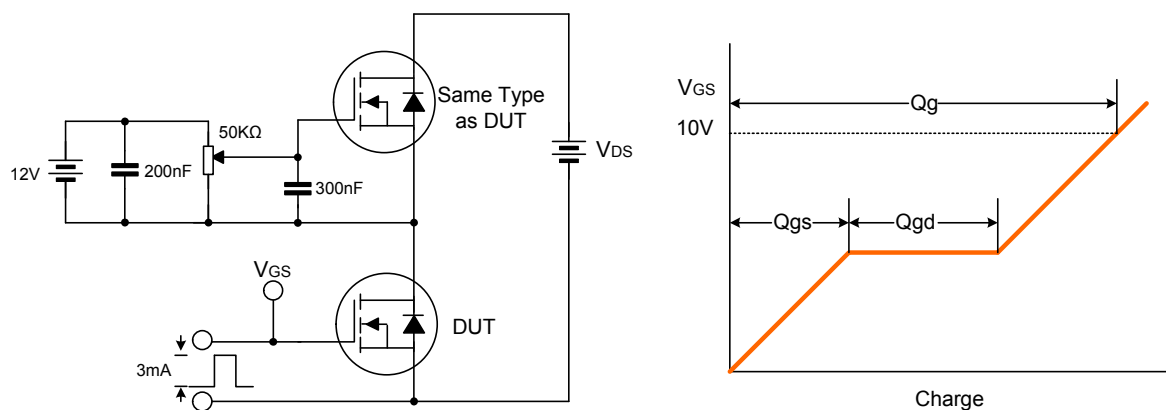


Figure 10. Max. Drain Current vs. Case Temperature

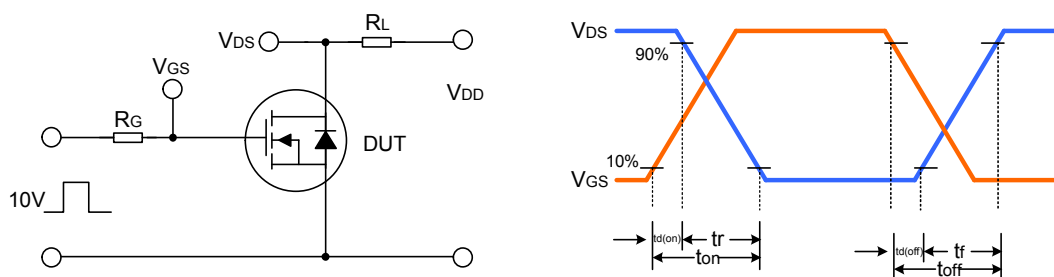


TYPICAL TEST CIRCUIT

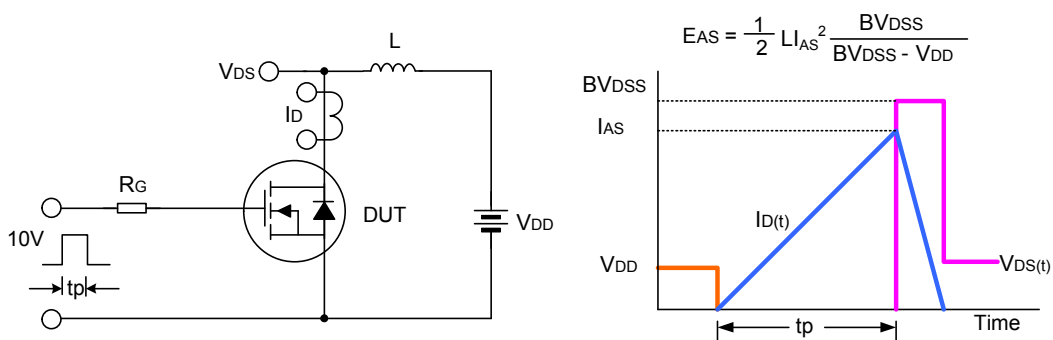
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



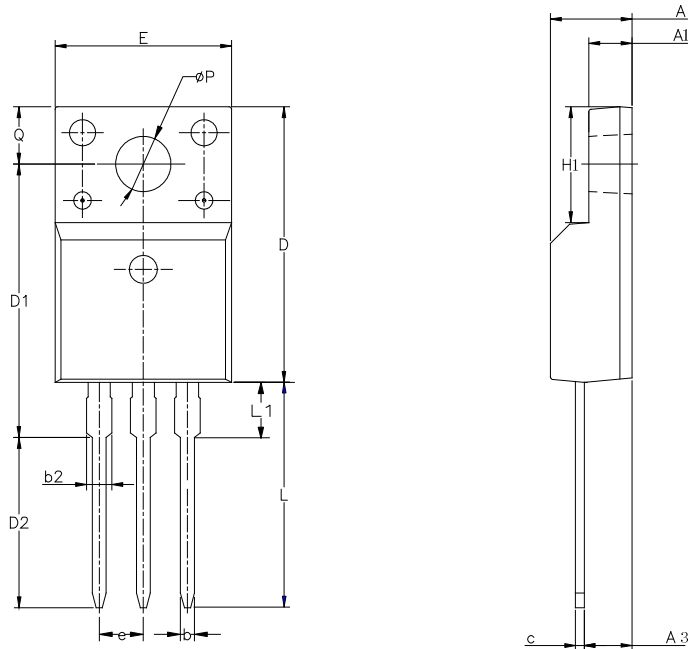
Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE

TO-220F-3L

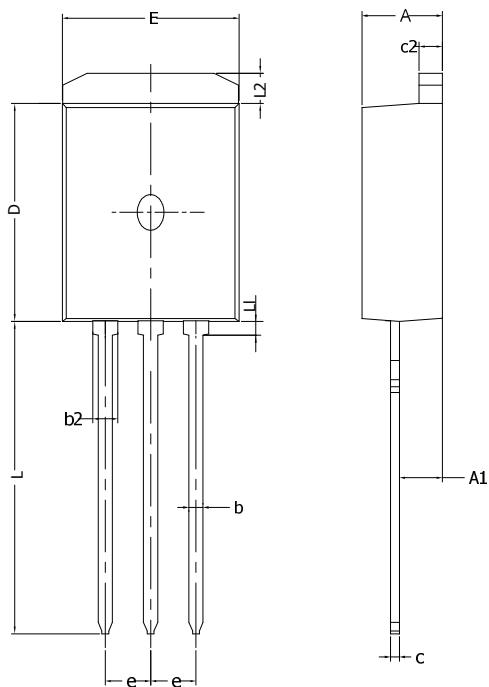
UNIT: mm



SYMBOL	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BCS		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	/	/	3.50
ϕP	3.00	3.18	3.40
Q	3.05	3.30	3.55

TO-262-3L

UNIT: mm

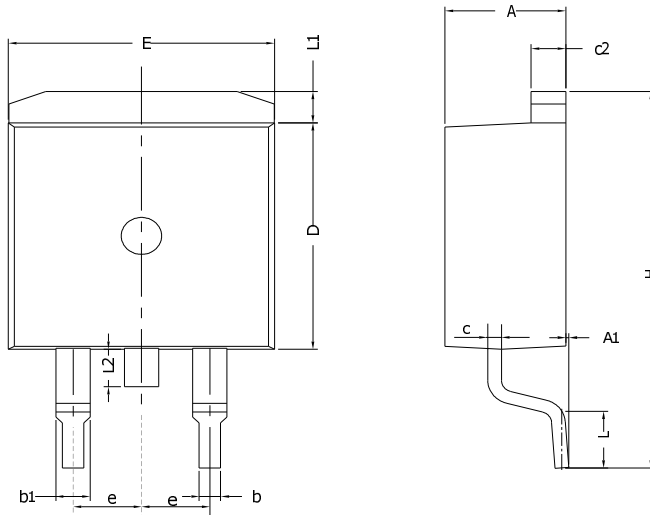


SYMBOL	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	2.20	---	2.92
b	0.71	0.80	0.90
b2	1.20	---	1.50
c	0.34	---	0.65
c2	1.22	1.30	1.35
D	8.38	---	9.30
E	9.80	10.16	10.54
e	2.54 BSC		
L	12.80	---	14.10
L1	---	---	0.75
L2	1.12	---	1.42

PACKAGE OUTLINE(continued)

TO-263-2L

UNIT: mm



SYMBOL	MIN	NOM	MAX
A	4.30	4.57	4.72
A1	0	0.1	0.25
b	0.71	0.81	0.91
c	0.30	---	0.60
c2	1.17	1.27	1.37
D	8.50	---	9.35
E	9.80	---	10.45
e	2.54BSC		
H	14.70	---	15.75
L	2.00	2.30	2.74
L1	1.12	1.27	1.42
L2	---	---	1.75

Disclaimer :

- Silan reserves the right to make changes to the information herein for the improvement of the design and performance without prior notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- All semiconductor products malfunction or fail with some probability under special conditions. When using Silan products in system design or complete machine manufacturing, it is the responsibility of the buyer to comply with the safety standards strictly and take essential measures to avoid situations in which a malfunction or failure of such Silan products could cause loss of body injury or damage to property.
- Silan will supply the best possible product for customers!

Part No.:	SVF12N65CF/K/S	Document Type:	Datasheet
Copyright:	HANGZHOU SILAN MICROELECTRONICS CO.,LTD	Website:	http://www.silan.com.cn

Rev.: 2.2

Revision History:

1. Update Figure1
-

Rev.: 2.1

Revision History:

1. Modify characteristics of Capacitance and Fig 5
 2. Update the package outline of TO-262-3L
-

Rev.: 2.0

Revision History:

1. Delete the package outline of TO-220FQ-3L
-

Rev.: 1.9

Revision History:

1. Update characteristics
 2. Update figure 5 and 6
 3. Update the package outline of TO-262-3L
-

Rev.: 1.8

Revision History:

1. Delete the package outline of TO-262L-3L
 2. Update the solid figure of TO-220FQ-3L
-

Rev.: 1.7

Revision History:

1. Update the package outline of TO-262-3L
-

Rev.: 1.6

Revision History:

1. Modify the Typical Characteristics
-

Rev.: 1.5

Revision History:

1. Add the package of TO-262L-3L
 2. Add the package of TO-220FQ-3L
 3. Modify the package outline of TO-262-3L and TO-263-2L
-

Rev.: 1.4

Revision History:

1. Modify the package information of TO-220F-3L
-

Rev.: 1.3

Revision History:

1. Modify the package information
 2. Add the package of TO-263-2L and related information
-

Rev.: 1.2

Revision History:

1. Add the package of TO-262-3L
-

Rev.: 1.1

Revision History:

1. Modify the thermal characteristics
-

Rev.: 1.0

Revision History:

1. First release
-